

2653
IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

IN THE MATTER OF:

HOSONO

FILED: April 16, 2001

SERIAL NO. 09/836,135

DOCKET NO: MM4424

06-14-03
S+



FOR: IMPROVED DISK DRIVE UNIT AND DISK DRIVE METHOD

INFORMATION DISCLOSURE STATEMENT

Hon. Commissioner of Patents & Trademarks
Washington, DC 20231
Attn: BOX DD

SIR:

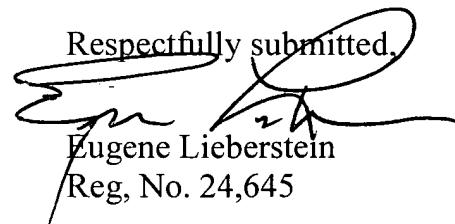
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APR 14 2003

Technology Center 2600

This Information Disclosure Statement is being filed in accordance with the provisions of 37 CFR 1.97 before the issuance of a first Office Action. Any necessary fee should be deducted from Deposit Account No. 01-1944.

This Information Disclosure Statement is being filed to officially make of record the references cited in the attached PTO Form 1449. Copies of these references are also enclosed.

Respectfully submitted,

Eugene Lieberstein
Reg. No. 24,645

MAILING CERTIFICATE

I hereby certify that this correspondence is being deposited with the U.S. Postal Service as first class mail in an envelope addressed: Commissioner of Patents & Trademarks, Washington, DC 20231 on April 8, 2003.

Dated: 4/08/03

Signed: 

INFORMATION DISCLOSURE STATEMENT

It is requested that the following documents, cited in the office action of the corresponding Japanese patent application 2000-119438, be notified to the USPTO:

- (1) Japanese Laid-Open Patent Application, No. 3-228262, a copy and an English abstract of which are enclosed herewith;
- (2) Japanese Laid-Open Patent Application, No. 4-362569, a copy and an English abstract of which are enclosed herewith;
- (3) Japanese Laid-Open Patent Application, No. 8-077691, a copy and an English abstract of which are enclosed herewith;
- (4) Japanese Laid-Open Patent Application, No. 8-339614, a copy and an English abstract of which are enclosed herewith;
- (5) Japanese Laid-Open Patent Application, No. 61-170959, a copy and a brief explanation in English of which are enclosed herewith;
- (6) Japanese Laid-Open Patent Application, No. 11-306641, a copy and an English abstract of which are enclosed herewith, and
- (7) Japanese Laid-Open Patent Application, No. 11-306661, a copy and an English abstract of which are enclosed herewith.